NOTES: I. MATERIALS AND FINISHES:

BODY - BeCu, GOLD PLATING, CONTACT - BeCu, GOLD PLATING INSULATOR - PTFE

2. ELECTRICAL:

A. IMPEDANCE: 50 OHM
B. FREQUENCY RANGE: DC - 20 GHz

3. MECHANICAL:

A. DURABILTIY: 100 CYCLES MIN.
B. ENGAGEMENT FORCE: 15 LB [67 N] MAX

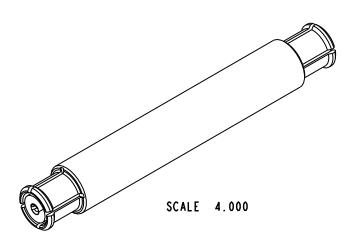
DISINGAGEMENT FORCE: 2 LB [9 N] MIN TEMERATURE RANGE: -65° C TO 165° C

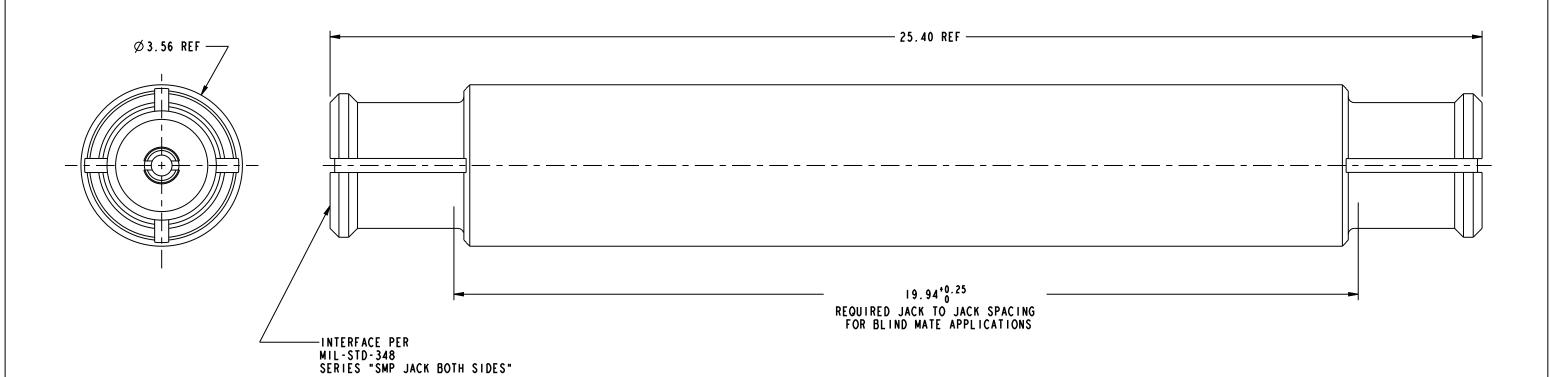
E. TEMERA 4. PACKAGING:

A. QUANTITY: SINGLE PACK
B. MARKING: BAG TO BE MARKED
"AMPHENOL, SMP-FSBA-254, AND DATE CODE"

THIRD ANGLE PROJ. 🕀 🖯 REVISIONS

REV DESCRIPTION DATE ECO APPR RELEASE TO MFG 47635 PNE Α





CUSTOMER OUTLINE DRAWING

ALL OTHER SHEETS ARE FOR INTERNAL USE ONLY

UNLESS OTHERWISE SPEC			
0.5 - 6mm	6 - 30mm	30 - 120mm	ANGLES
±0.lmm	± 0.2 mm	± 0.3mm	±1°
NOTICE - These drawings, s	pecifications, or o	other data (I) are, o	ind remain the
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rights to permitting such	holder or any other	r sperson to manufact	ure, use or sell any
product, process or design	i, patented or other	wsie, that may in an	y way be related to
or disclosed by said drawi	ings, specification:	s, or other data,	

MATERIAL SEE NOTES	DRAWN K.LI	DATE 02 - Jul - 09	TIT
SEE NOTES	ENGINEER PADMANABHAN E	DATE 26-Mar-09	
REFERENCE	APPROVED	DATE	1
EAR # 3477 AND SMP-FSBA-224	S. HSIEH	2 - Jul - 09	SCALE
CONFIGURATION LEVEL: Prototype	CAD FILE		DW
FINISH	Root Folder/SMP/SMP-FS	BA-254	

ASSEMBLY SMP, F-F, ADAPTER			Amphenol RF Danbury CT USA, Tainan, Taiwan, Shenzhen, China www.amphenolrf.com
			DRAWING NO.SMP-FSBA-254
LE: 12.0:1.0 SHEE	.0:1.0 SHEET 2 OF 2		ITEM NO.SMP-FSBA-254
DWG SIZE CODE	: ID	REV	
В 748	368	Α	PART NO.SMP-FSBA-254

Mouser Electronics

Authorized Distributor

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